

Electronic Patent Application Fee Transmittal

Application Number:	10552370
Filing Date:	26-Jul-2006
Title of Invention:	SOAP-MOLDING DIE
First Named Inventor/Applicant Name:	Takashi Nakano
Filer:	Marvin Jay Spivak/Mimi Chanthaphone
Attorney Docket Number:	279330US3PCT

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Utility Appl Issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

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Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	3	3	9
Total in USD (\$)				1819